

CLEAN VERSION OF AMENDED CLAIMS - BASF/NAE 1032/99

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3. The solid composition as claimed in claim 1, characterized in that the bonds which can be activated with actinic radiation comprise carbon-hydrogen single bonds or carbon-carbon, carbon-oxygen, carbon -nitrogen, carbon-phosphorus or carbon-silicon single bonds or double bonds, especially carbon-carbon double bonds.
4. The solid composition as claimed in claim 1, characterized in that the groups (a) are selected from the group containing (meth)acrylate, ethacrylate, crotonate, cinnamate, vinyl ether, vinyl ester, dicyclopentadienyl, norbornenyl, isoprenyl, isopropenyl, allyl and butenyl groups; dicyclopentadienyl ether, norbornenyl ether, isoprenyl ether, isopropenyl ether, allyl ether or butenyl ether groups, and dicyclopentadienyl ester, norbornenyl ester, isoprenyl ester, isopropenyl ester, allyl ester and butenyl ester groups.
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6. The solid composition as claimed in claim 1, characterized in that, based on its overall weight, it contains from 5.0 to 95% by weight of the (meth)acrylate copolymer (A) and from 95 to 5.0% by weight of the compound (B).
7. The solid composition as claimed in claim 1, characterized in that the groups (a) in the compound (B) are attached to the parent structure by way of urethane, ester, ether and/or amide groups.
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9. The solid composition as claimed in claim 1, characterized in that the compound (B) is amorphous, partly crystalline, or crystalline.
10. The solid composition as claimed in claim 1, characterized in that the compound (B) has a melting range or melting point in the temperature range from 40 to

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130°C.

A3 11. The solid composition as claimed in claim 1, characterized in that the compound (B) has a melt viscosity at 130°C of from 50 to 20 000 mPas.

12. The solid composition as claimed in claim 1, characterized in that the parent structure of the compound (B) is of low molecular mass, oligomeric and/or polymeric.

A4 14. The solid composition as claimed in claim 12, characterized in that the oligomeric and/or polymeric parent structure is derived from random, alternating and/or block, linear, branched, hyperbranched, dendrimeric and/or comb polyaddition resins, polycondensation resins and/or addition (co)polymers of ethylenically unsaturated monomers.

A5 16. The solid composition as claimed in claim 1, characterized in that the methacrylate copolymer (A) and/or the compound (B) comprise at least one chemically bonded stabilizer (e).

19. The solid composition as claimed in claim 16, characterized in that the chemically bonded stabilizer (e) is present in the solid compound (B).

A6 20. The solid composition as claimed in claim 1, characterized in that the compound (B) contains reactive functional groups (c) which are able to undergo thermal crosslinking reactions with groups (c) of its own kind and/or with complementary functional groups (b) which are also present in the methacrylate copolymer (A) and/or in at least one crosslinking agent.

21. The solid composition as claimed in claim 1, characterized in that the

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methacrylate copolymer (A) and/or the compound (B) comprises chemically bonded photoinitiators and/or photoco-initiators.

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22. The use of the solid composition as claimed in claim 1 as coating materials, adhesives or sealing compounds which can be crosslinked thermally and/or with actinic radiation, or to produce coating materials, adhesives or sealing compounds which can be crosslinked thermally and/or with actinic radiation.
23. Coating materials, adhesives or sealing compounds comprising at least solid compositions as claimed in claim 1.

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27. The coating materials, adhesives or sealing compounds as claimed in claim 23, characterized in that at least one further additive is present therein.
28. The coating materials, adhesives or sealing compounds as claimed in claim 23, characterized in that they are present as powders, powder slurries, or a solution or dispersion in organic solvents.
29. The use of the coating materials, adhesives or sealing compounds as claimed in claim 23 to produce coatings, adhesive films or seals for primed or unprimed substrates.
30. A process for producing coatings, adhesive films or seals for primed or unprimed substrates, wherein
- (1) at least one coating material and/or adhesive and/or at least one sealing compound as claimed in claim 23 in the form
- of
- (1.1) a melt,

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- (1.2) a powder,
- (1.3) a powder slurry or
- (1.4) a dispersion or a solution in at least one organic solvent
- is applied to the primed or unprimed substrate,
- (2) the resulting powder slurry film (1.3) or the resulting film of a dispersion or a solution (1.4) is dried or the resulting film of the melt (1.1) is caused to solidify or is maintained in the melted state by heating,
- (3) the resulting solid film (1.2), (1.3) or (1.4) is melted by heating, and
- (4) the melted film which results in process step (2) or (3),
- (4.1) in the melted state,
- (4.2) on solidification and/or
- (4.3) after solidification,
- is cured with actinic radiation.

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32. The process as claimed in claim 30, characterized in that heating is carried out with near infrared (NIR) light.
33. Coatings, adhesive films or seals on primed or unprimed substrates, by the process as claimed in claim 30.
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